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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of: Mezenner

Docket: TI-33824

Application No.: 10/749,277

Examiner: Dinh, Jack

Filed: 12/31/2003

Art Unit: 2873

For: Via Adhesion in Multi-Layer

Conf. No.: 8542

MEMS Structure

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FACSIMILE COVER SHEET

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<input type="checkbox"/> DECLARATION (# Pages)	<input type="checkbox"/> NOTICE OF APPEAL + dup (pages)
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<input type="checkbox"/> DIVISIONAL APP'N	<input type="checkbox"/> PETITION
	<input type="checkbox"/> IDS
NAME OF INVENTOR(S): Rabah Mezenner	
TITLE OF INVENTION: Via Adhesion in Multi-Layer MEMS Structure	
TI FILE NO.: TI-33824	DEPOSIT ACCT. NO.: 20-0668
FAXED: 05/05/2006 DUE: ATTY/SECY: CAB:ss	
RECEIPT DATE & SERIAL NO.: Application No.: 10/749,277 Notice of Allowance: 03/09/2006	

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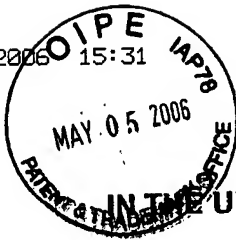
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COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

May 5, 2006

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	5 MAY 2006
Charles A. Brill	Date

Dear Sir:

In response to the Notice of Allowance and Fee(s) Due mailed March 9, 2006,
Applicant submits the following comments:

REMARKS

The Applicant agrees with the Examiner's conclusions of patentability, without necessarily agreeing with or acquiescing in the Examiner's reasoning or comments. The Applicant submits that the claims of the above-identified application are allowable because the prior art fails to anticipate or render obvious the invention as claimed.

Respectfully submitted,



Charles A. Brill
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